

ABSTRACT OF THE DISCLOSURE

An infrared data communication module (A) includes a substrate (1) having a surface (1a) for mounting a group (E) of components including a light emitting element (2), a light receiving element (3) and an IC element (4), and a molded body (5) formed of a molding resin to cover the entire surface (1a) of the substrate (1) for sealing the group (E) of components. The surface (1a) of the substrate (1) is formed with one or a plurality of jumper pads (11a, 11b) formed by plating a conductive film with gold. Each jumper pad (11a, 11b) is partially or entirely spaced from an edge of the substrate.